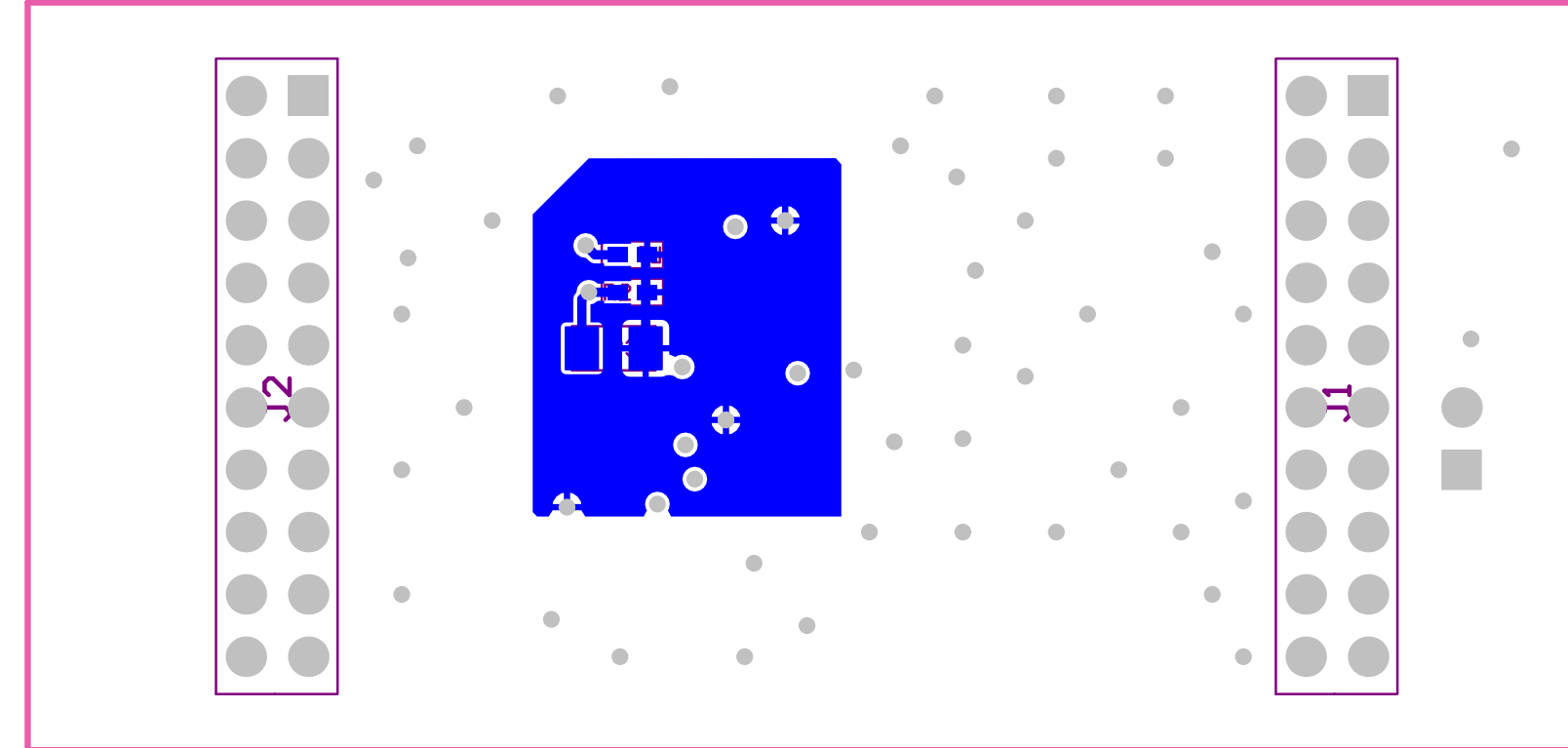


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01575	REV: A0	SVN REV: Not In VersionControl
Top Layer	TID #: TIDA-01575		
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 1/25/2018 9:05:38 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01575	REV: A0	SVN REV: Not In VersionControl
	TID #: TIDA-01575	Bottom Layer	
PLOT NAME = Bottom Layer Assembly Drawing	GENERATED : 1/25/2018	9:05:38 AM	TEXAS INSTRUMENTS

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